



TECHNICAL DATA

P-2000 HOT MELT PURGE

INTRODUCTION

P-2000 is a safe, non-hazardous, highly effective hot melt-cleaning compound. It has a pleasant odor and is environmentally friendly. Use of P-2000 helps reduce downtime and increases productivity. Prevents binding of applicator wheels, erratic pump stroking and loosens charred material. Also prevents nozzle clogging and hose constrictions.

P-2000 hot melt purge is designed for flushing reactive PUR hot melt adhesives from hot melt application equipment to prevent the cured hot melt from seizing up the nozzles and curing inside the applicator.

Also used for cleaning general hot melt equipment that contains EVA, polyethylene, rubber based PSAs and polyamides to remove oxidized and charred material.

PHYSICAL PROPERTIES

Appearance	Green
Melting Point	176°F
Application Temperature	250-325°F
Viscosity	Approx. 30,000 cps @ 250°F Approx. 6,000 cps @ 325°F
Storage Stability	Store in a cool, dry place
Shelf Life	Indefinite

F.D.A. All components of this product conform to the following F.D.A. regulations subject to the extraction limitations thereof:

C.F.R. Section 175.105 Adhesives

SUGGESTED USES

P-2000 dissolves thermoplastic hot melt adhesives by dropping the adhesive viscosity and loosening charred material, which can then be flushed from the system, eliminating the waste of purging large quantities of adhesives through equipment.

Use of P-2000 as part of a regular preventative maintenance program eliminates costly unscheduled line shutdowns.

Upon start-up after the purging process, remove any excess P-2000 purge out of the nozzle prior to assembly using the reactive PUR hot melts.

P-2000 can be used on food packaging glue lines.

PURGE FORM:

10 oz cartridges (i.e. PAM 500K, REKA TR 80.3, TR 50.3, 3M, etc).
5-gallon metal pails and 55 gallon drums for bulk equipment.
50 lbs boxes in pellet form.

INSTRUCTIONS

Use P-2000 at the processing temperature of the adhesive in the system.

1. Drain the system of all hot melt adhesive. Mechanically clean the feed area as needed, then remove nozzles and screens to prevent blockage from loosened degraded material.
2. For systems with nozzle clogging problems or char build up; fill the melt pot with P-2000 and melt to adhesive application temperature. Run the pump until the green purge exits the hose/feed line for the nozzles. Turn off the pump and maintain the purge cleaner at the adhesive application temperature or 325°F (which ever is the higher of the two) for one hour. After the one-hour period (longer cook times are OK), drain or pump the purge out of the melt pot. Turn the pump off. Install clean filters and the nozzles, and then add enough purge to the melt pot for the purging of the hose and nozzles. After the purge has reached application temperature, pump the remaining purge through the system.
3. For systems that need to change adhesives: fill the melt pot with P-2000 and melt to adhesive application temperature. Maintain the purge cleaner at the adhesive application temperature or 325°F (which ever is the lower of the two) for 15 minutes. Pump the purge through the system for five minutes. Drain or pump the remaining purge out of the melt pot.
4. For hot melt application guns: use a 10 oz. Cartridge to purge nozzles for cartridge style guns. Use P-2000 pellets to purge and clean bulk loaded guns. Fill the bulk-loading gun with P-2000 and heat to 325°F. When melted, extrude purge until the extruded material is green. Then completely fill the unit with purge and permit it to heat to 325°F. To purge, extrude the purge after 15 minutes at temperature or for cleaning char, heat for one hour and then remove the P-2000. After the use of the P-2000, flush the gun with the next hot melt to be used.
5. Add enough new hot melt adhesive to the melt pot to flush the purge from the system. This usually is about 1/3 of the melt pot.
6. After the adhesive is at application temperature, pump it through the system.
7. The system is now ready for use.
8. Contact Ellsworth Adhesives at 800-877-8378 for questions that may be unique to your equipment.

ADVANTAGES OF P-2000 vs. WAX

- P-2000 has more body to it and will push and flush hot melt out of the hose and nozzles, where wax is too thin when melted to do any cleansing. Wax will simply run next to the hot melt without push or carrying it out of the equipment.
- Wax, being very low viscosity, has a tendency to be a splash hazard.
- P-2000 will penetrate the char and loosen, where wax cannot do this.

These suggestions and data are based on information we believe to be reliable. They are offered in good faith, but without guarantee, as conditions and methods of use of our products are beyond our control. We recommend that the prospective user determine the suitability of our materials and suggestions before adopting them on a commercial scale. Suggestions for uses of our products or the inclusion of descriptive material from patents and the citation of specific patents should not be understood as recommending the use of our products in violation of any patent or as permission or license to use any patents.

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